

ON Semiconductor®

FGH40T65SHD 650 V, 40 A Field Stop Trench IGBT

Features

- Maximum Junction Temperature : T_J =175°C
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- Low Saturation Voltage: V_{CE(sat)} =1.6 V(Typ.) @ I_C = 40 A
- + 100% of the Parts Tested for $I_{\text{LM}}(1)$
- High Input Impedance
- Fast Switching
- Tighten Parameter Distribution
- RoHS Compliant

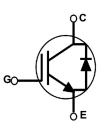


Using novel field stop IGBT technology, ON Semiconductor's new series of field stop 3rd generation IGBTs offer the optimum performance for solar inverter, UPS, welder, telecom, ESS and PFC applica-tions where low conduction and switching losses are essential.

Applications

• Solar Inverter, UPS, Welder, Telecom, ESS, PFC





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Description		FGH40T65SHD-F155	Unit
V _{CES}	Collector to Emitter Voltage	ollector to Emitter Voltage		V
V _{GES}	Gate to Emitter Voltage		± 20	V
	Transient Gate to Emitter Voltage		± 30	V
1	Collector Current	@ T _C = 25°C	80	А
IC	Collector Current	@ T _C = 100°C	40	А
I _{LM (1)}	Pulsed Collector Current	@ T _C = 25°C	120	А
I _{CM (2)}	Pulsed Collector Current		120	А
I _F	Diode Forward Current	@ T _C = 25°C	40	А
'F	Diode Forward Current	@ T _C = 100°C	20	А
I _{FM (2)}	Pulsed Diode Maximum Forward Curren	120	А	
P _D	Maximum Power Dissipation	@ T _C = 25°C	268	W
. D	Maximum Power Dissipation	@ T _C = 100°C	134	W
TJ	Operating Junction Temperature		-55 to +175	°C
T _{stg}	Storage Temperature Range		-55 to +175	°C
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

Notes:

1. V_{CC} = 400 V, V_{GE} = 15 V, I_C =120 A, R_G = 30 Ω , Inductive Load

2. Repetitive rating: Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	FGH40T65SHD-F155	Unit	
R _{0JC} (IGBT)	Thermal Resistance, Junction to Case, Max.	0.56	°C/W	
$R_{\theta JC}$ (Diode)	Thermal Resistance, Junction to Case, Max.	1.71	°C/W	
R _{θJA}	Thermal Resistance, Junction to Ambient, Max.	40	°C/W	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGH40T65SHD-F155	FGH40T65SHD	TO-247 G03	Tube	-	-	30

Electrical Characteristics of the IGBT $T_{C} = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	teristics					
BV _{CES}	Collector to Emitter Breakdown Voltage	V _{GE} = 0V, I _C = 1 mA	650	-	-	V
ΔBV _{CES} / ΔT _J	Temperature Coefficient of Breakdown Voltage	$I_{\rm C}$ = 1 mA, Reference to 25°C	-	0.6	-	V/ºC
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0 V$	-	-	250	μA
I _{GES}	G-E Leakage Current	V _{GE} = V _{GES} , V _{CE} = 0 V	-	-	±400	nA
On Charac	teristics					
V _{GE(th)}	G-E Threshold Voltage	$I_{\rm C}$ = 40 mA, $V_{\rm CE}$ = $V_{\rm GE}$	4.0	5.5	7.5	V
		$I_{\rm C} = 40$ A, $V_{\rm GE} = 15$ V	-	1.6	2.1	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	$I_{C} = 40 \text{ A}, V_{GE} = 15 \text{ V},$ $T_{C} = 175^{\circ}\text{C}$	-	2.14	-	V
Dynamic C	haracteristics					
C _{ies}	Input Capacitance		-	1995	-	pF
C _{oes}	Output Capacitance	V _{CE} = 30 V _, V _{GE} = 0 V, f = 1MHz	-	70	-	pF
C _{res}	Reverse Transfer Capacitance		-	23	-	pF
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time		-	19.2	-	ns
t _r	Rise Time	-	-	34.4	-	ns
t _{d(off)}	Turn-Off Delay Time	V _{CC} = 400 V, I _C = 40 A,	-	65.6	-	ns
t _f	Fall Time	R _G = 6 Ω, V _{GE} = 15 V,	-	9.6	-	ns
Eon	Turn-On Switching Loss	Inductive Load, $T_C = 25^{\circ}C$	-	1010	-	uJ
E _{off}	Turn-Off Switching Loss		-	297	-	uJ
E _{ts}	Total Switching Loss		-	1307	-	uJ
t _{d(on)}	Turn-On Delay Time		-	18.4	-	ns
t _r	Rise Time		-	32.8	-	ns
t _{d(off)}	Turn-Off Delay Time	V _{CC} = 400 V, I _C = 40 A,	-	71.2	-	ns
t _f	Fall Time	$R_G = 6 \Omega$, $V_{GE} = 15 V$,	-	14.4	-	ns
E _{on}	Turn-On Switching Loss	- Inductive Load, T _C = 175°C - -	-	1390	-	uJ
E _{off}	Turn-Off Switching Loss		-	541	-	uJ
E _{ts}	Total Switching Loss		-	1931	-	uJ

Electrical Characteristics of the IGBT (Continued)

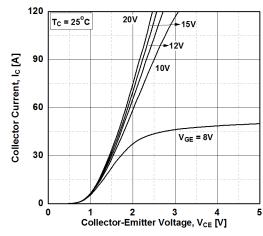
Symbol	Parameter	Test Conditions	Min.	Тур.	Max	Unit
Qg	Total Gate Charge	V _{CE} = 400 V, I _C = 40 A, V _{GE} = 15 V	-	72.2	-	nC
Q _{ge}	Gate to Emitter Charge		-	13.5	-	nC
Q _{gc}	Gate to Collector Charge		-	28.5	-	nC

Electrical Characteristics of the Diode $T_{C} = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Мах	Unit
V _{FM}	Diode Forward Voltage	I _F = 20 A	T _C = 25°C	-	2.2	2.8	V
*FM			T _C = 175°C	-	1.94	-	
E _{rec}	Reverse Recovery Energy		T _C = 175 ^o C	-	50	-	uJ
t _{rr} Diode Reverse Re	Diode Reverse Recovery Time	 _F =20 A, dI _F /dt = 200 A/μs	T _C = 25°C	-	31.8	-	ns
		-20 Λ, αιμαί - 200 Λ/μ3	T _C = 175 ^o C	-	192	-	
Q _{rr}	Diode Reverse Recovery Charge		T _C = 25 ^o C	-	50.6	-	nC
	2.000 Hore to the to th		T _C = 175 ^o C	-	699	-	

Typical Performance Characteristics







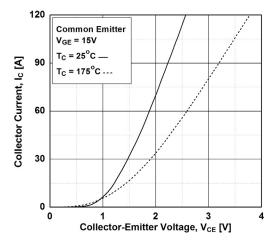


Figure 5. Saturation Voltage vs. V_{GE}

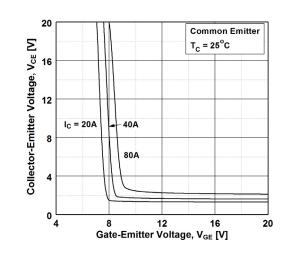
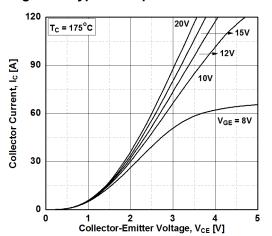
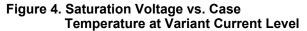


Figure 2. Typical Output Characteristics





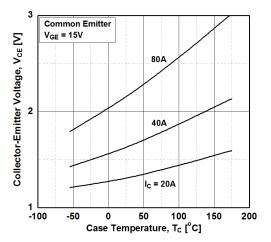
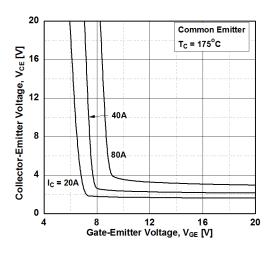


Figure 6. Saturation Voltage vs. V_{GE}



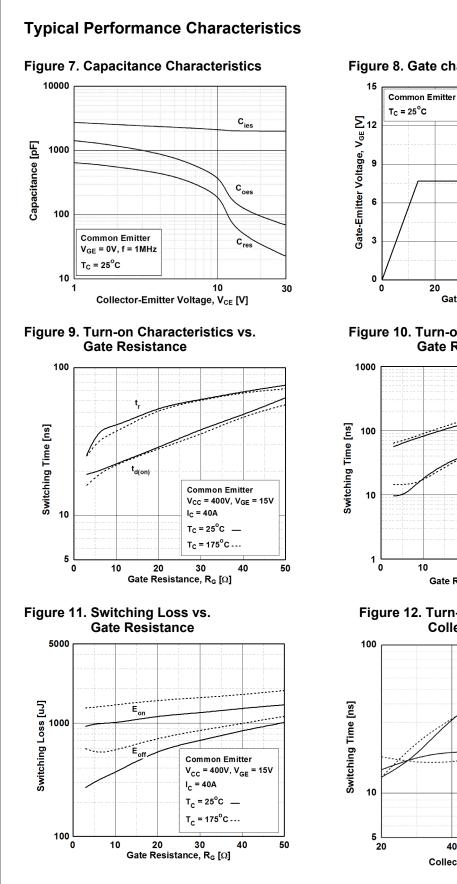
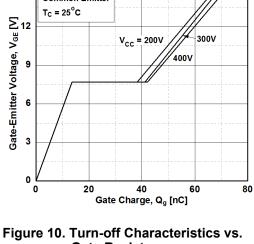


Figure 8. Gate charge Characteristics



Gate Resistance

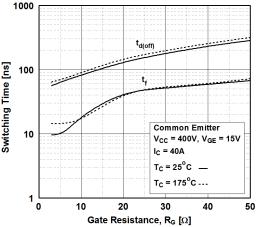
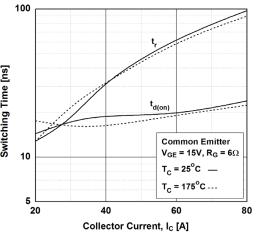
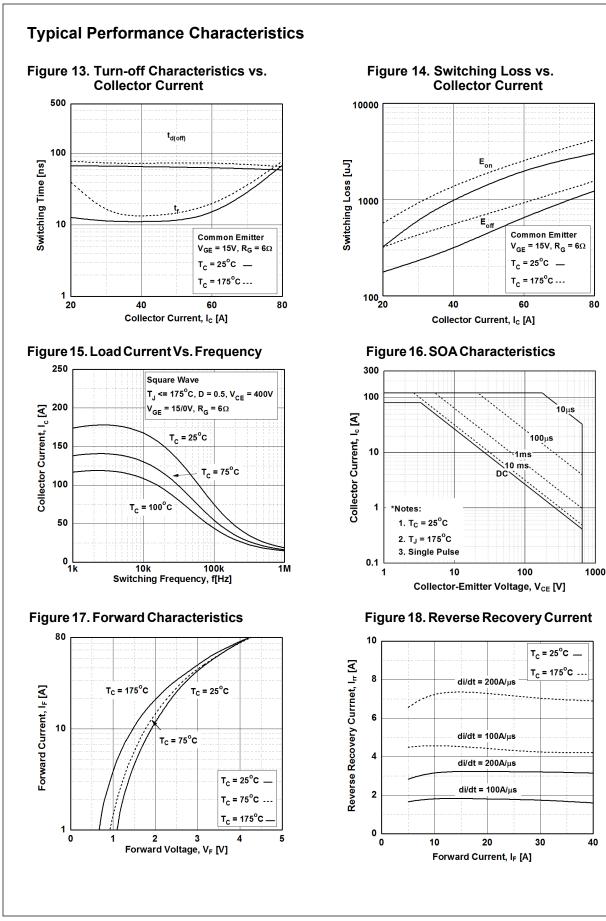


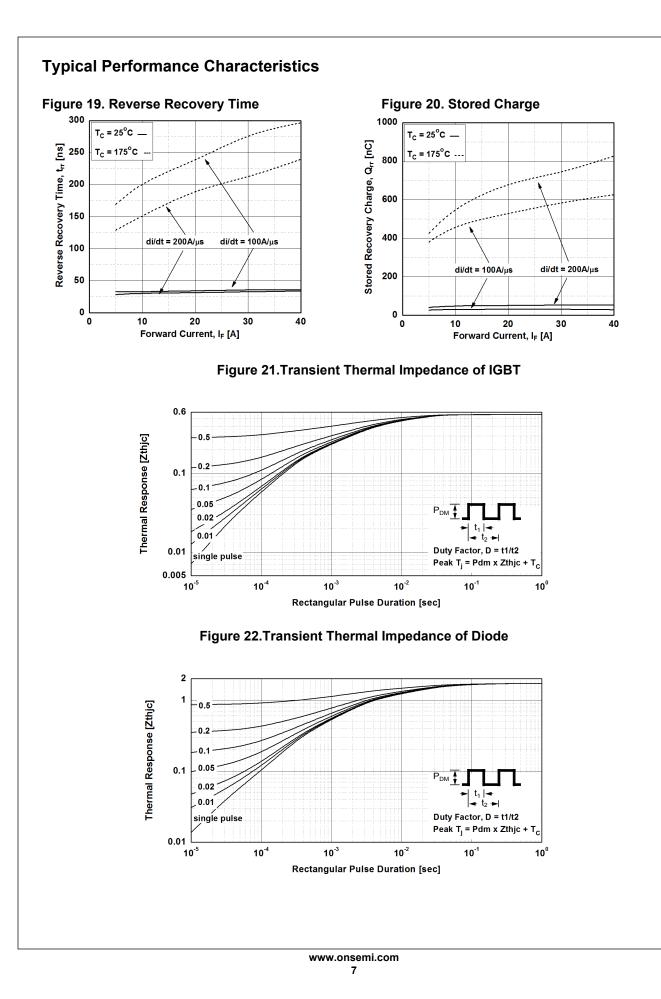
Figure 12. Turn-on Characteristics vs. **Collector Current**



80

40





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